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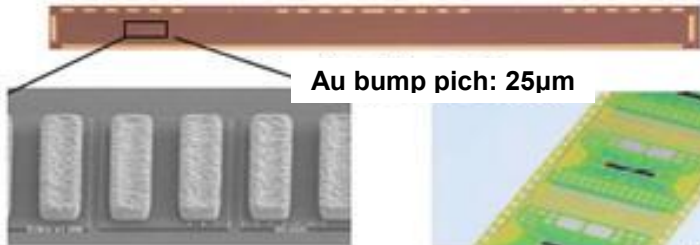
1998

Development of the COF for driving FPD screens

~ Packaging ~

In 1998, Hitachi Cable proposed FOC (Chip on Film) to semiconductor manufactures and display panel manufacturers as a packaging method to drive multi-terminal trend of driver ICs for TFT display devices, replacing the conventional TCP (Tape Carrier Package) using TAB (Tape Automated Bonding), which was a method of flip-chip connection of ICs with Au plated bumps to a TAB tape.

COF method can make the bump pitch of Au narrow, and provides a number of merits such as multi-terminals, reduction in chip size, improvement in yield, and gradually became a standard package for driver ICs for large liquid crystal TV, etc. and contributed to the progress of FPD (Flat Panel Display) for current thin and large size LCD TVs.



SEM micrograph of 25µm pitch Au bump



Example of chip mount of COF tape

